

Wireless Multi-Gigabit-Systems Workshop
TU Braunschweig, Germany

Beam-forming antenna array configurations for 60-GHz broadband communication

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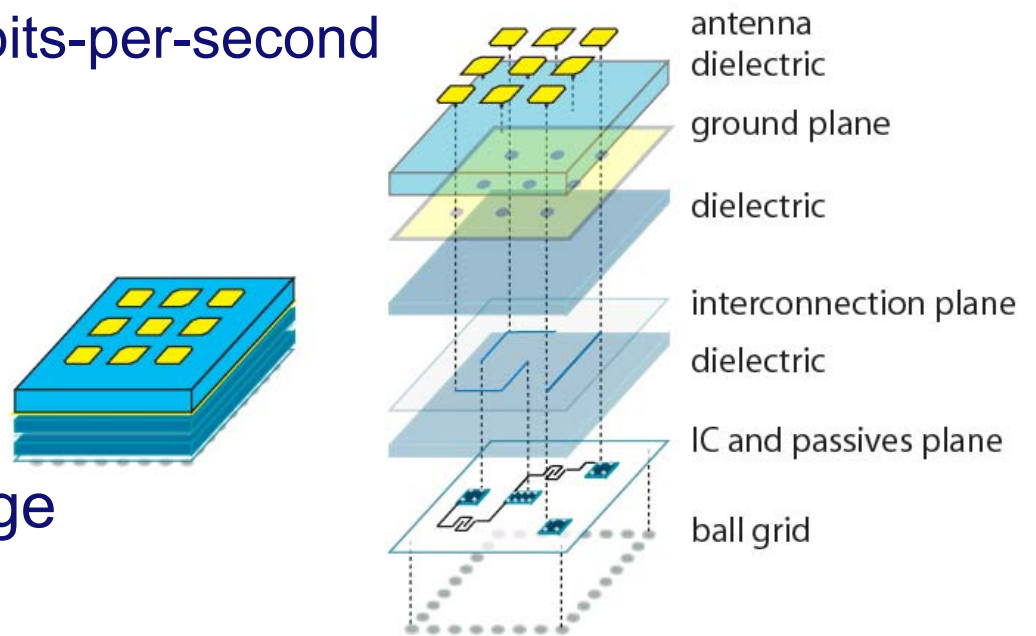
Where innovation starts

Outline

- Introduction
- Antenna element
- Measurements
- Antenna array
- Packaging
- 3D/Conformal antenna array

Introduction

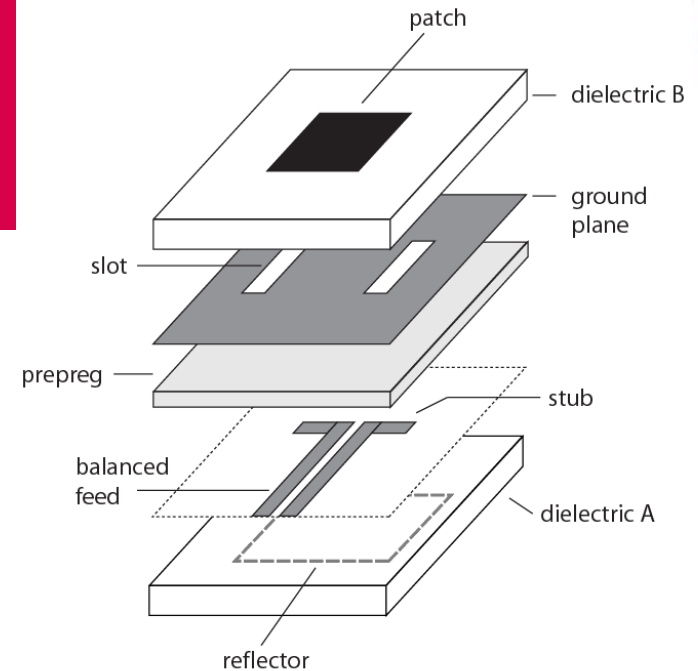
- Broadband communication in the 60 GHz band
 - Unlicensed bandwidth of around 7 GHz
 - Data rates of multiple gigabits-per-second
 - Applications
 - wireless USB 2.0
 - wireless HDTV
 - wireless gigabit ethernet
 - telecom backhaul
- Low-cost integrated package
 - transceiver chip-set
 - antenna
 - other passive components



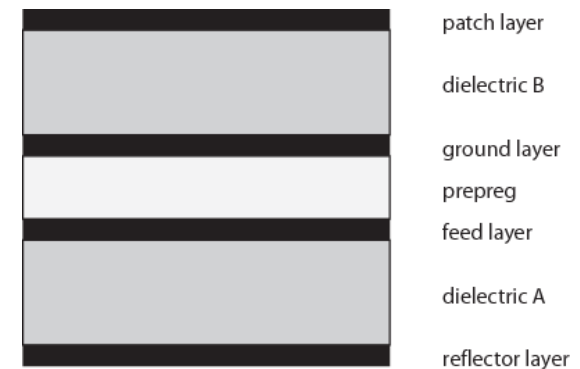
Antenna element

- Geometry

- Balanced-fed aperture-coupled patch antenna
 - realized in printed circuit-board
 - no vias
 - high radiation efficiency
 - >80%
 - bandwidth
 - 10-15 %



balanced-fed aperture-coupled patch antenna



PCB stack

Antenna element

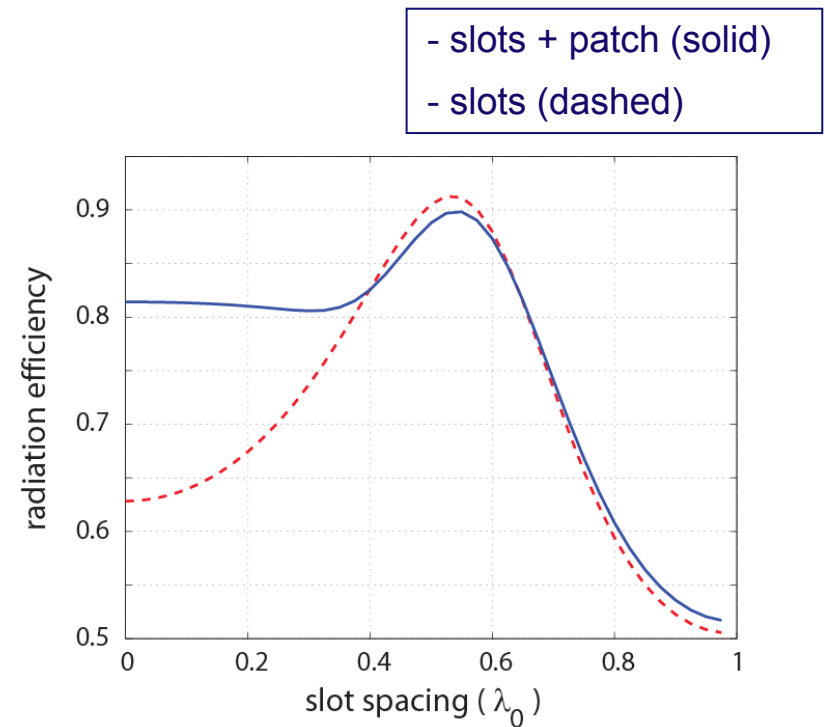
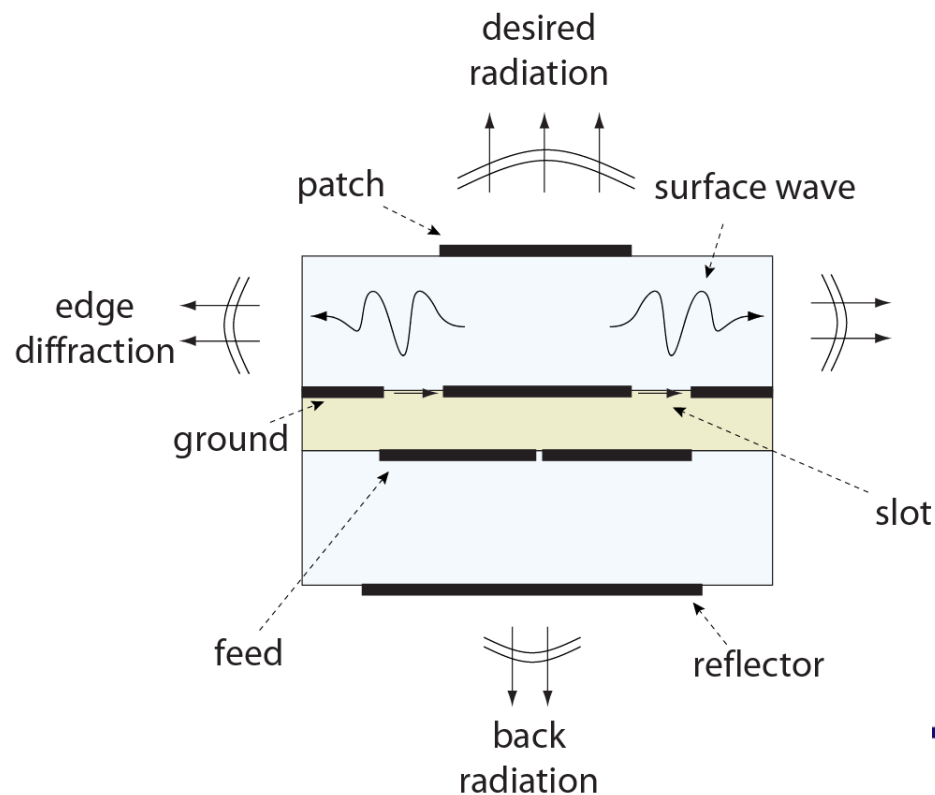
- Modelling

- Modelling
 - Green's functions for stratified media
 - Method of moments
 - spectral-domain representation
 - basis functions
 - entire-domain
 - rooftop
 - C++ implementation
- Sensitivity analysis and optimization

Antenna element

- Radiation efficiency

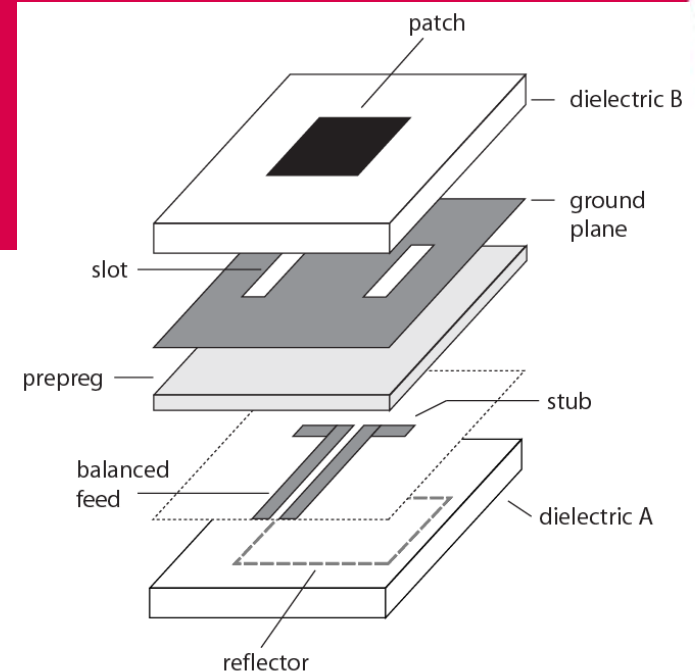
- slot spacing
 - cancel surface waves
 - efficiency > 80 %



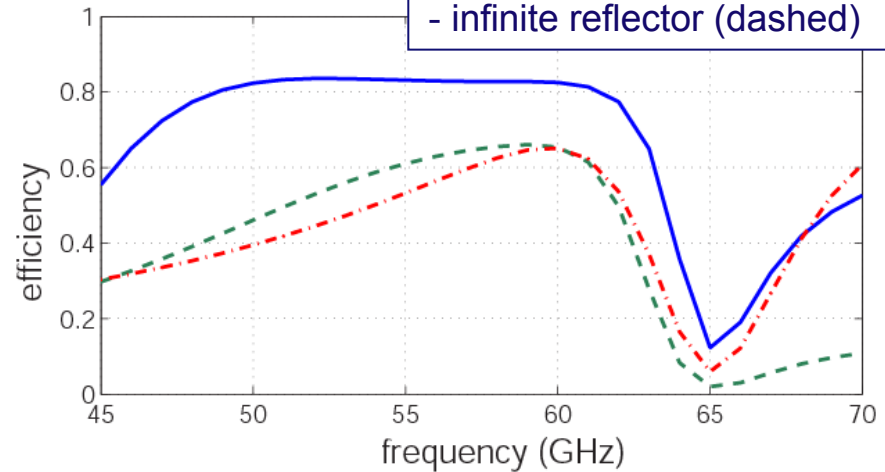
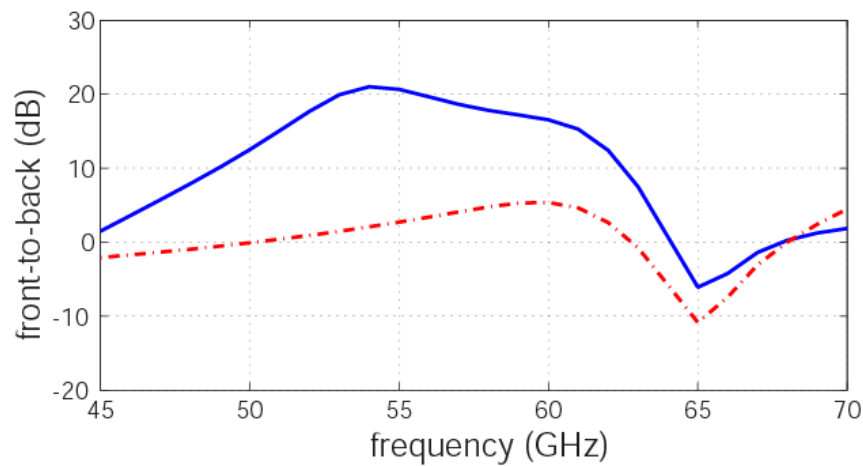
Antenna element

- Back radiation

- reflector element
- comparison
 - no reflector
 - infinite metal plane
 - finite metal reflector



- finite reflector (solid)
- no reflector (dash-dot)
- infinite reflector (dashed)



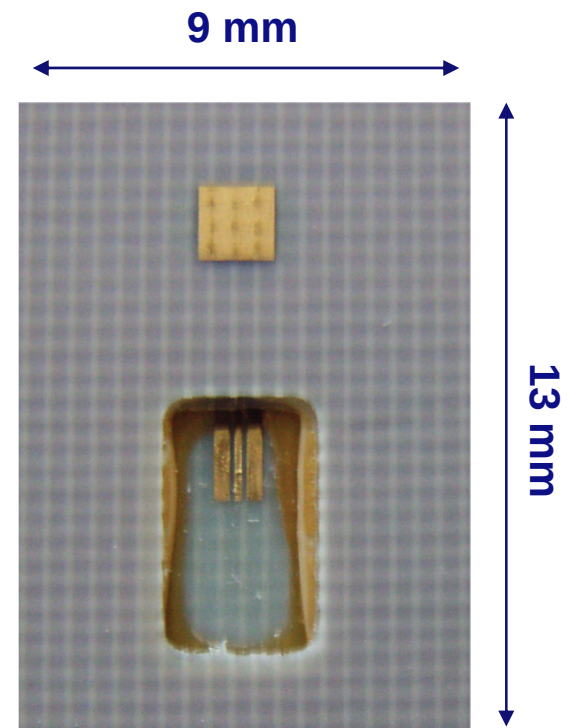
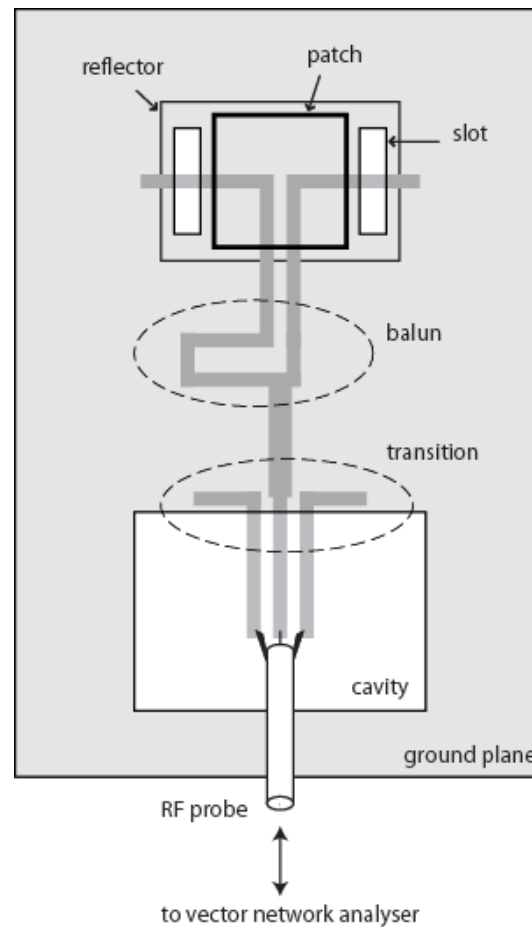
Measurements

- PCB layout

- GSG RF probe



- transition
 - CPW - MS
- balun

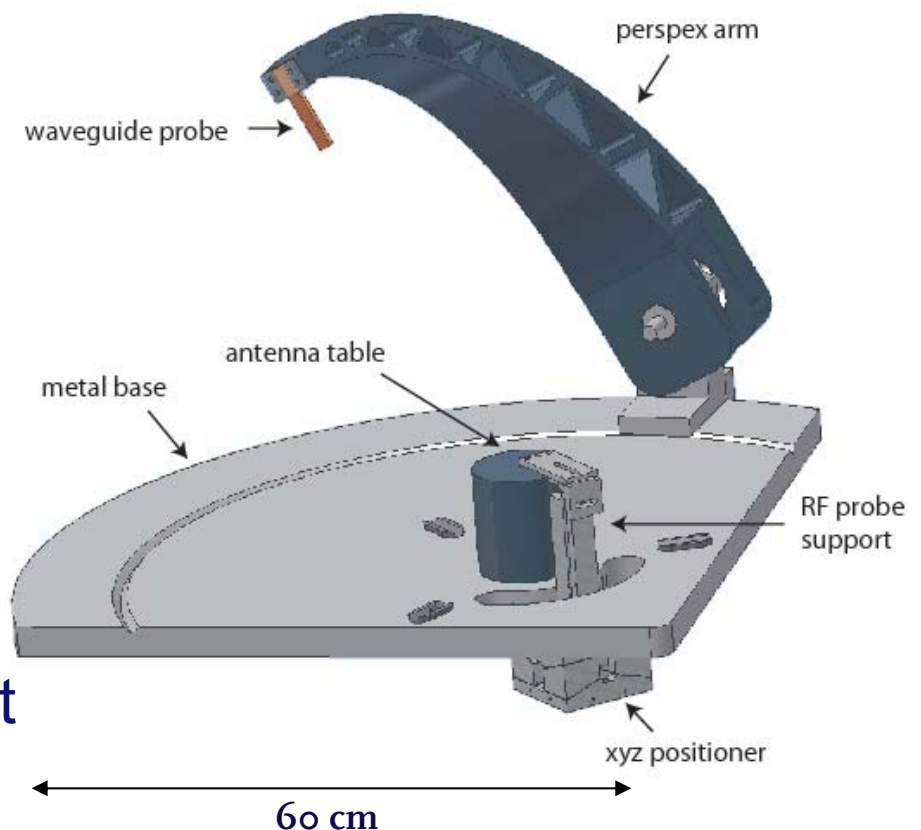


Measurements

- Radiation pattern

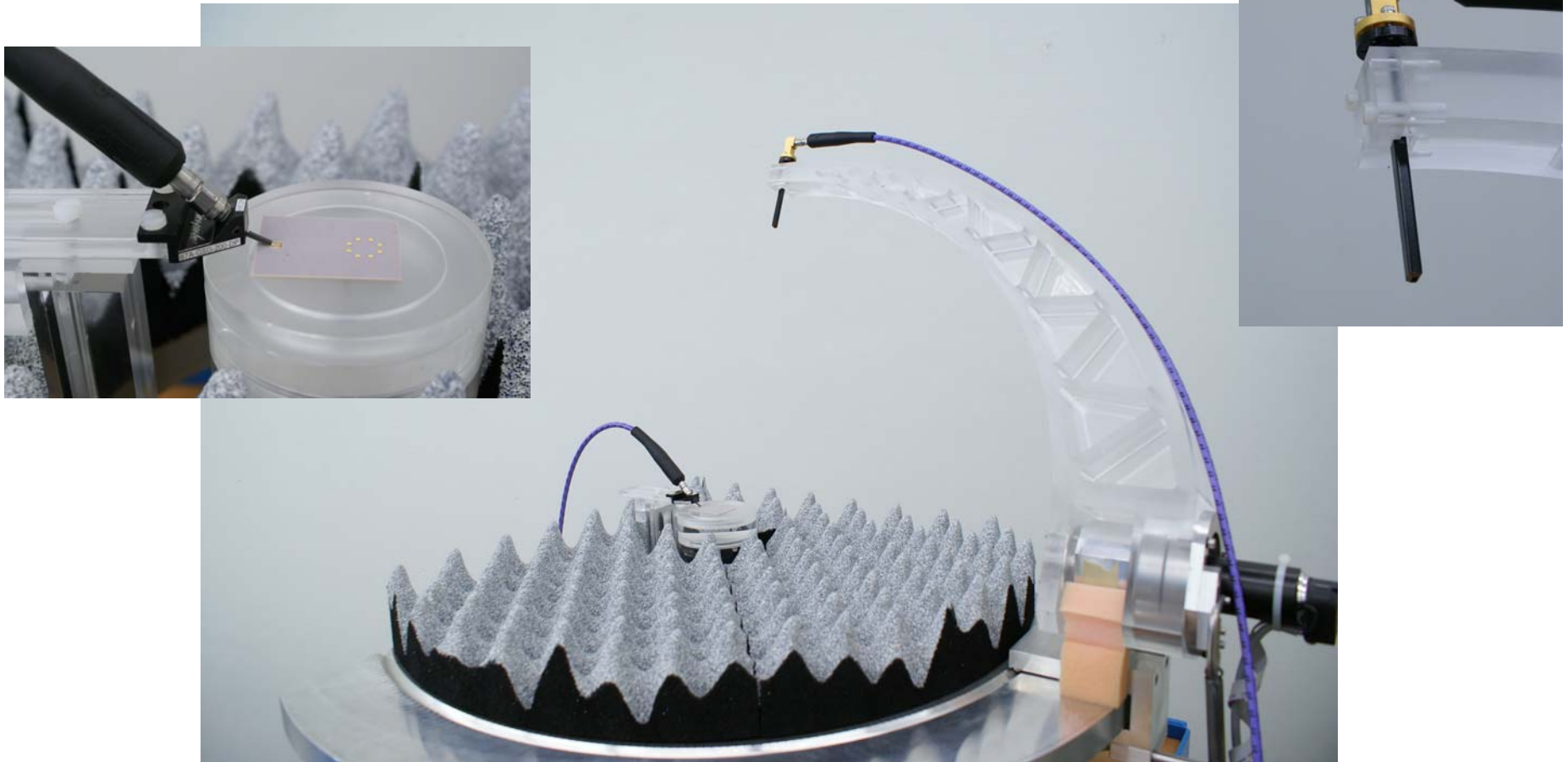
- Far-field radiation pattern measurement

- measures hemisphere
- designed to reduce unwanted scattering
- features
 - RF probe support
 - open-ended waveguide
 - 0, 45, 90 degrees
 - automated measurement
 - labview



Measurements

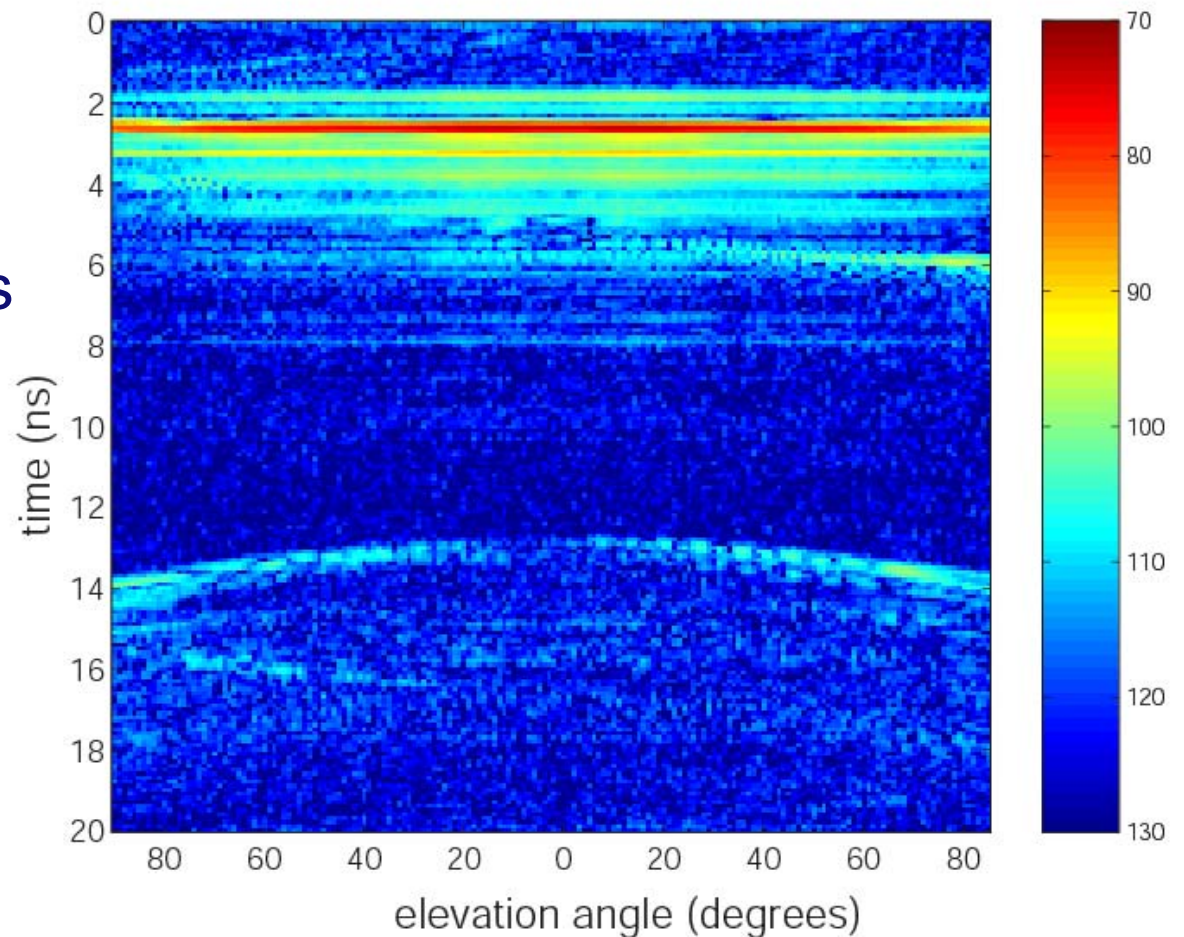
- Radiation pattern



Measurements

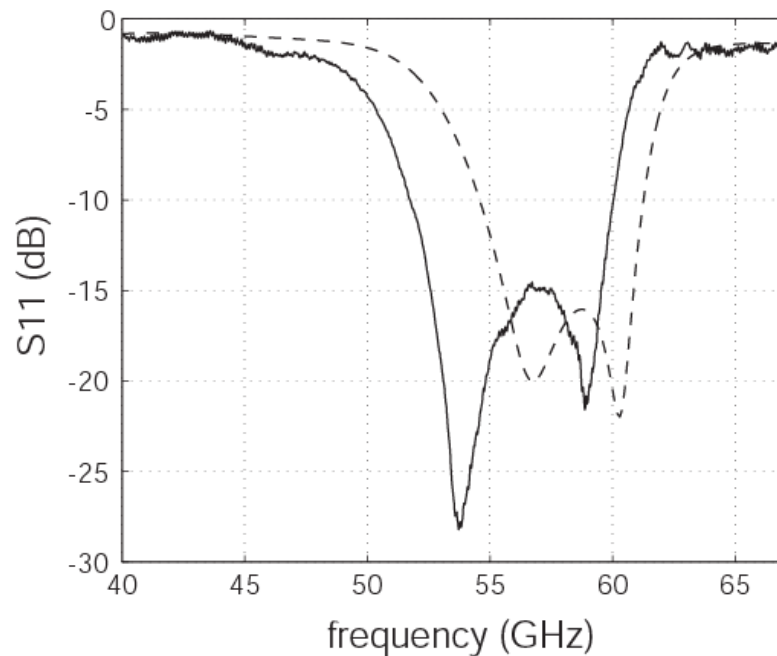
- Time gating

- Measurements in lab environment
- Time gating applied gate: $t = 1.8 - 4.9$ ns

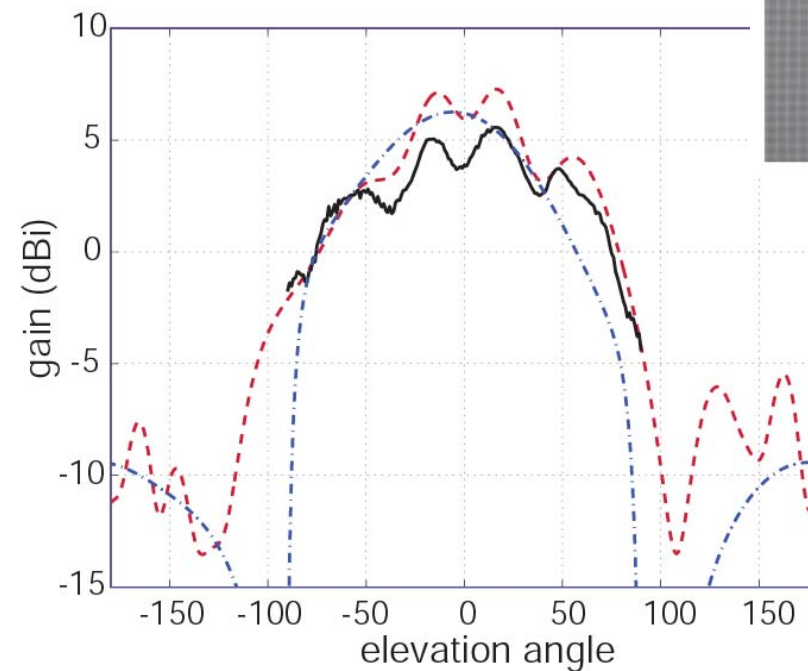


Measurements - Results

- Measurement results



- measurements (solid)
- simulation [Spark] (dashed)

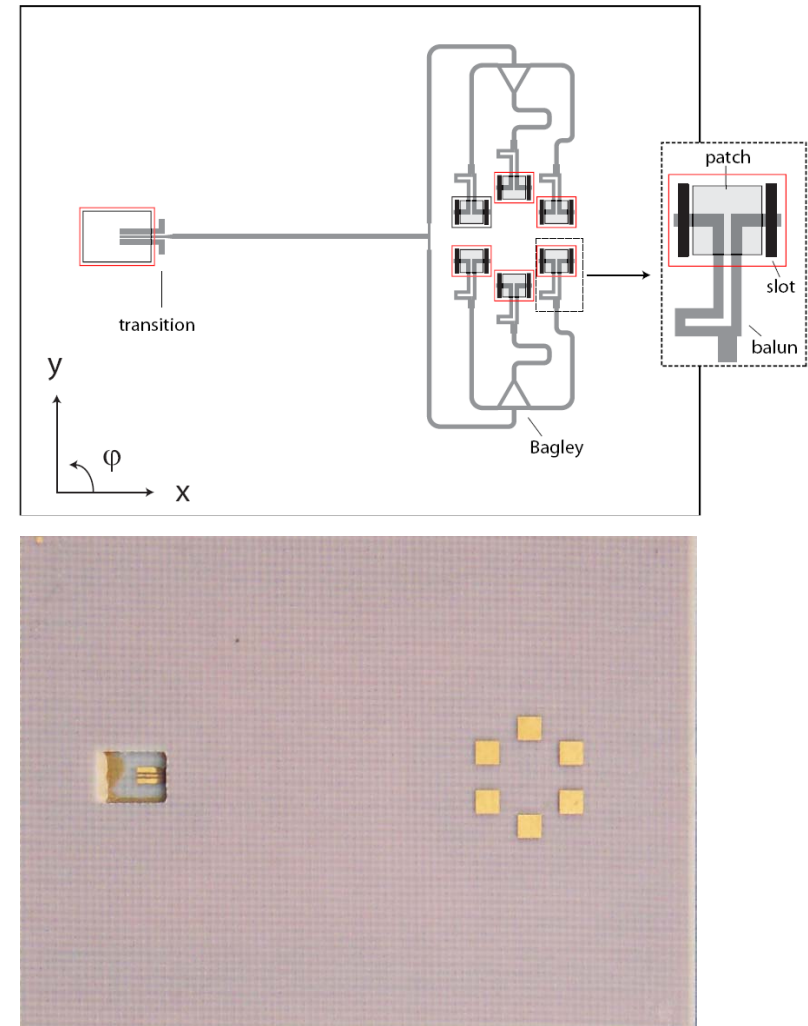


- measurements (solid)
- simulation [CST] (dashed)
- simulation [Spark] (dash-dot)



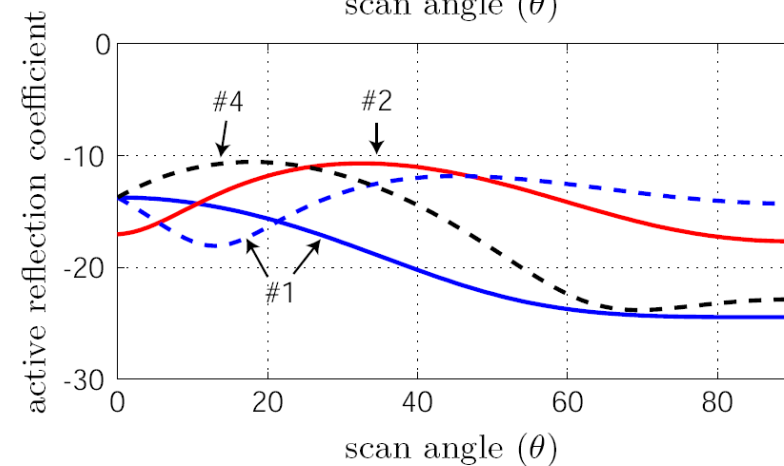
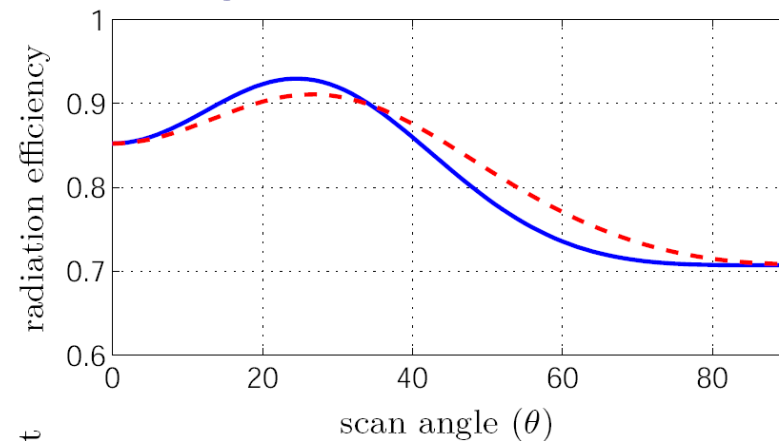
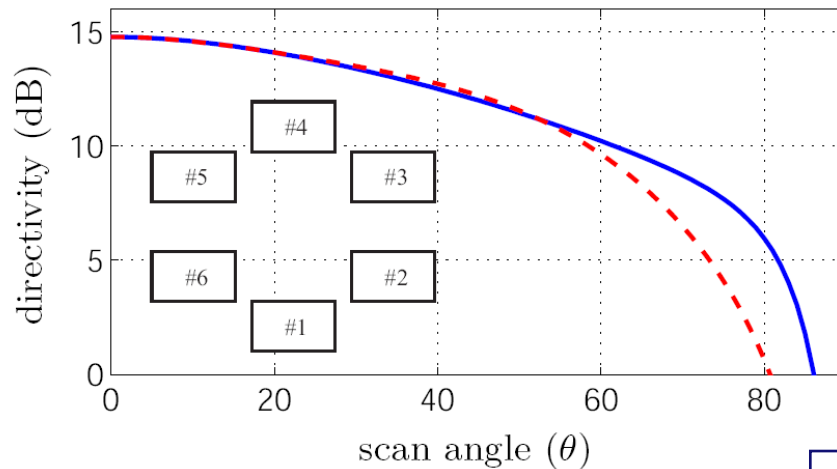
Antenna array

- Beam-forming antenna array
 - 6-element circular array
 - feed network designed for scan to $\theta = 0, 30, 45$ degrees
 - problem:
large feed-line losses
(1.3 dB/cm)



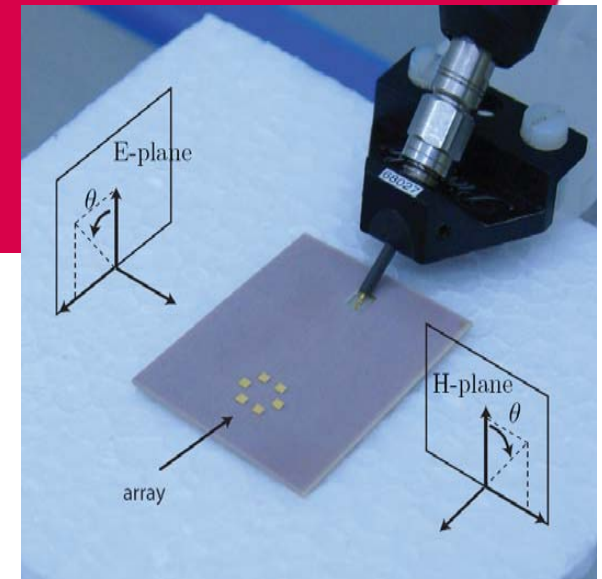
Antenna array - performance

- Performance as function of scan angle
 - no feed network
 - directivity
 - radiation efficiency
 - reflection coefficient

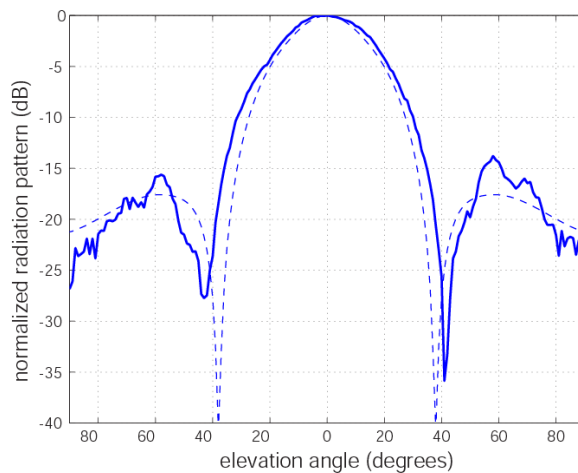


Antenna array - Results

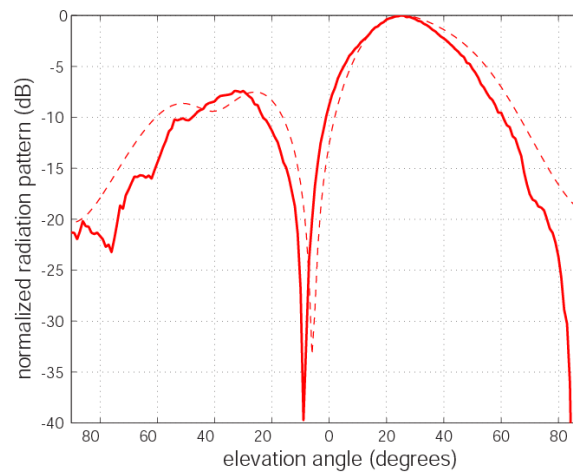
- Measurement results
 - beam-forming to 0, 30, 45 degrees



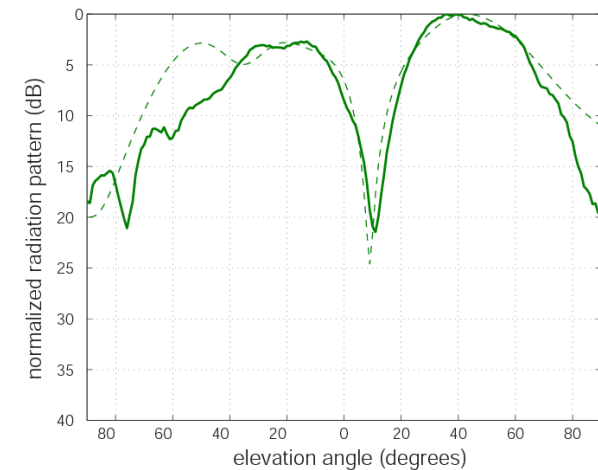
broadside



30 degrees

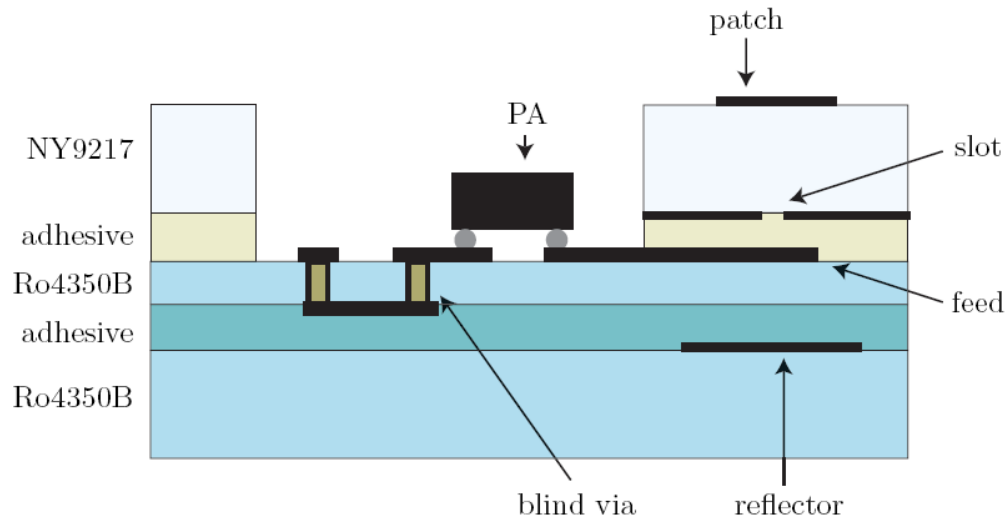


45 degrees

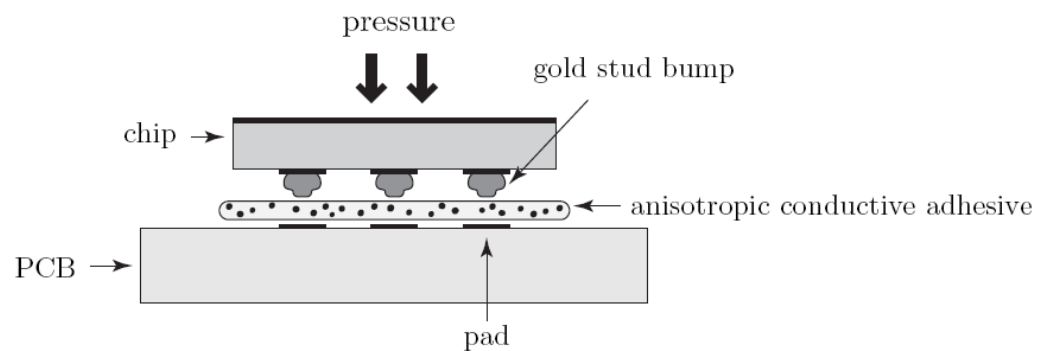


- simulation (dashed)
- measurement (solid)

Packaging - PCB stack



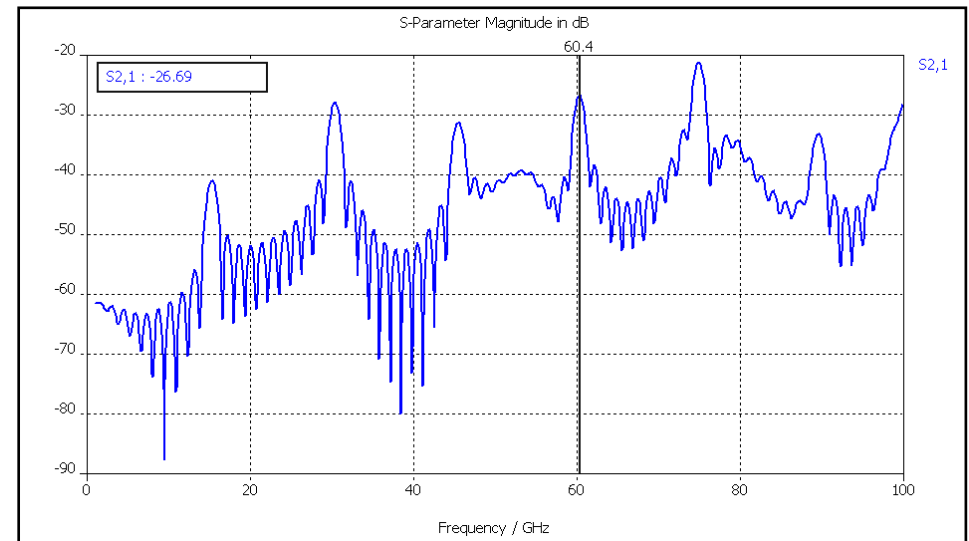
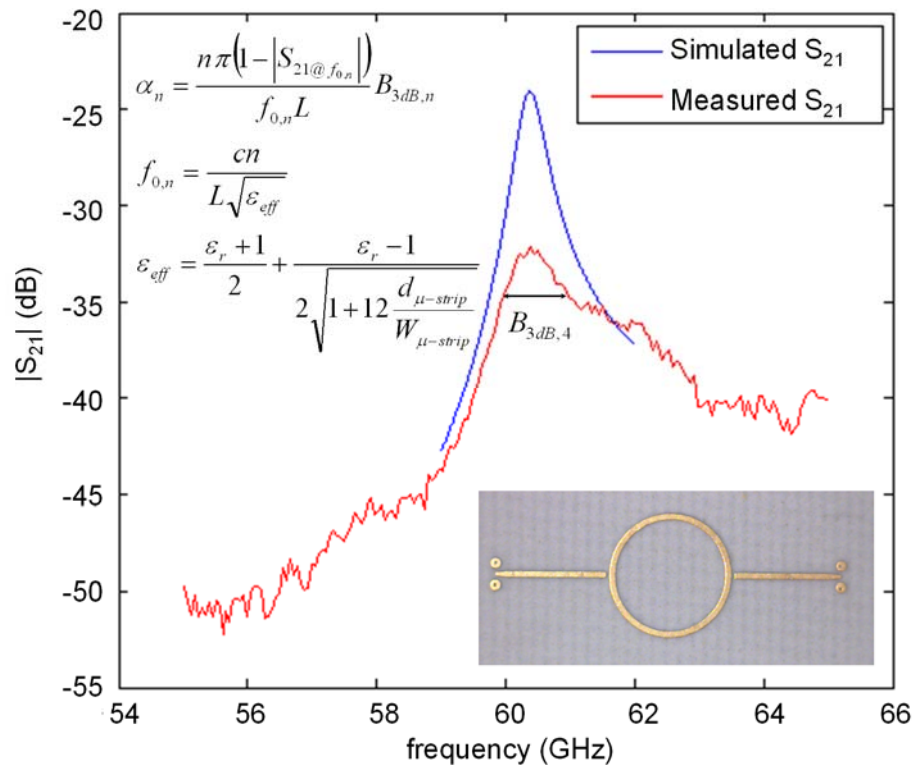
- Teflon-based materials
- ceramic materials
- vias



Packaging

- Material characterization

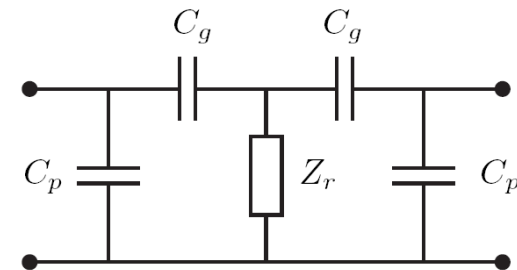
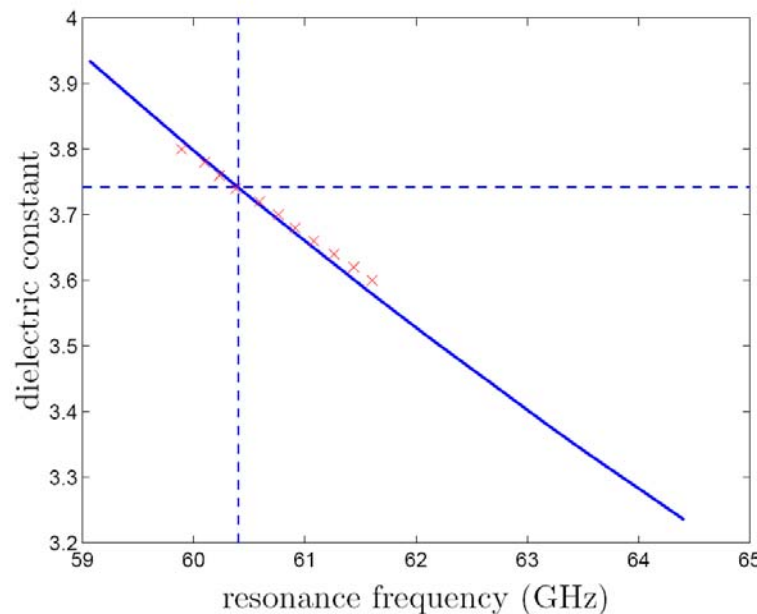
Microstrip Ring Resonator



Packaging

- Material characterisation

- Circuit model [1]
 - incorporate loading effect microstrip lines
 - determine dielectric constant



$$Z_r = \frac{Z_0}{2} \coth\left(\frac{\gamma L}{2}\right)$$

[1] J. Bray and L. Roy, "Microwave characterization of a microstrip line using a two-port ring resonator with an improved lumped-element model," IEEE MTT, May 2003

Packaging

- Material characterisation

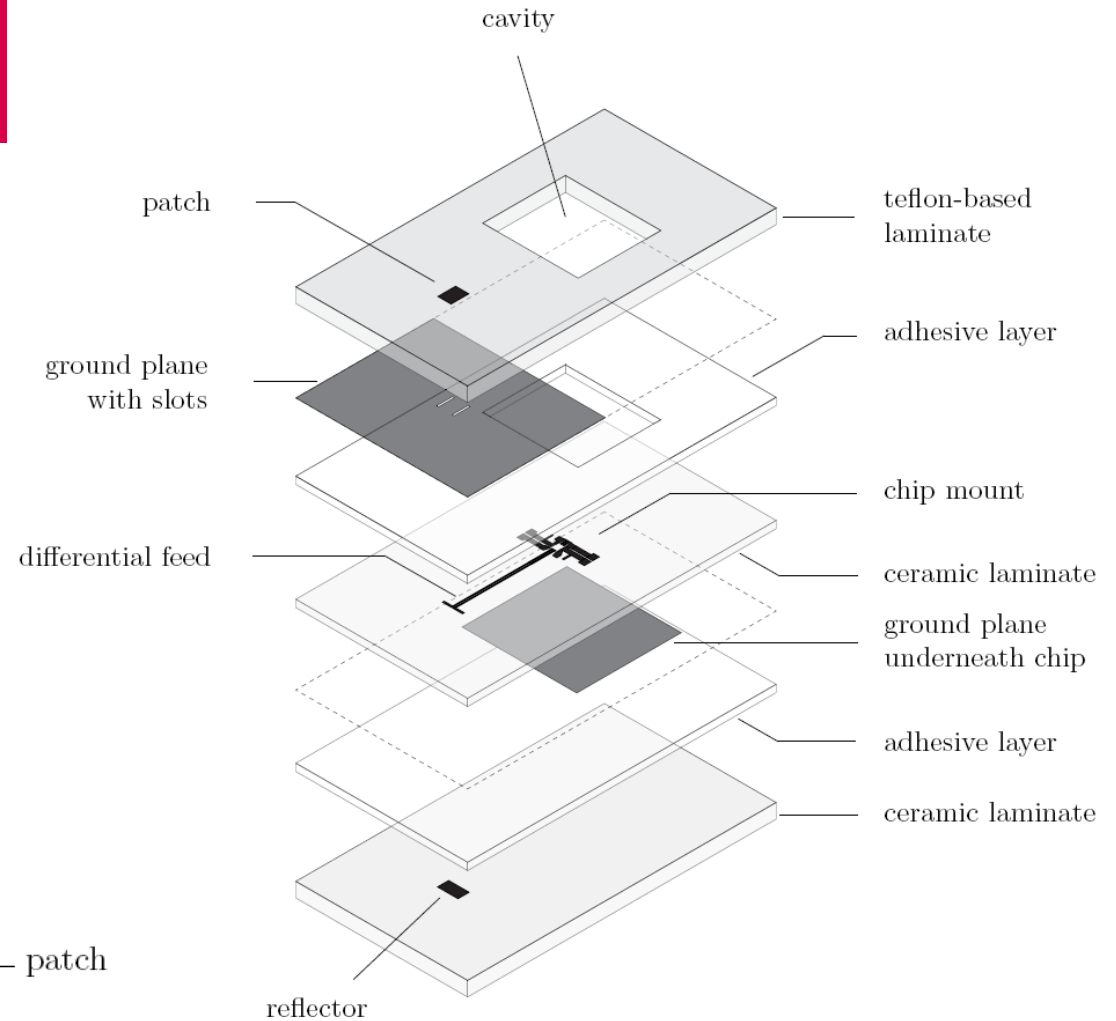
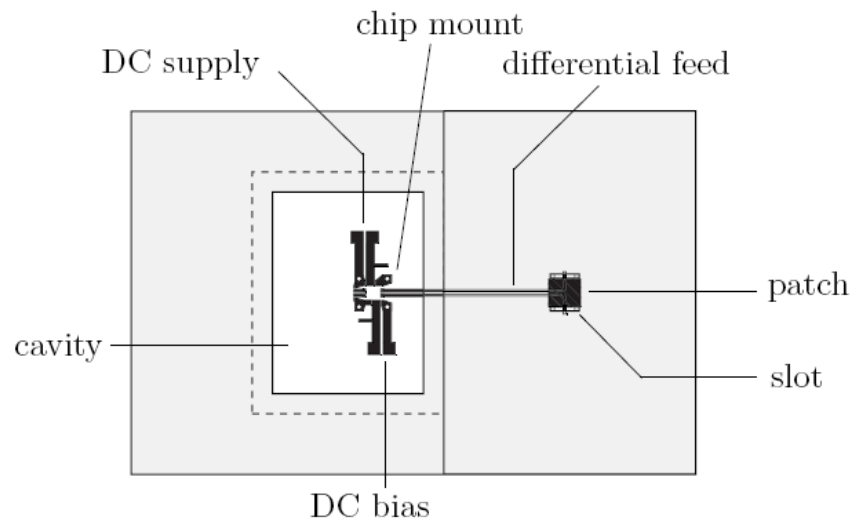
- RO4350B
- data sheet (10 GHz)

$$\square \epsilon_r = 3.66$$

n	$f_{0,n}$ [GHz]	$B_{3\text{dB},n}$ [GHz]	ϵ_r	attenuation [dB/cm]
1	15.24	0.49	3.67	0.38
2	30.46	0.69	3.66	0.53
3	45.55	1.0	3.69	0.77
4	60.42	1.3	3.74	1.0

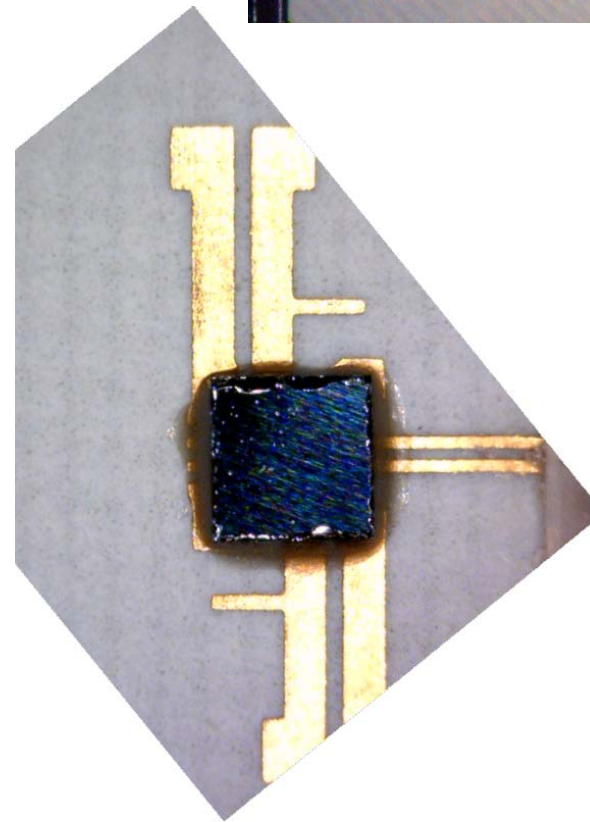
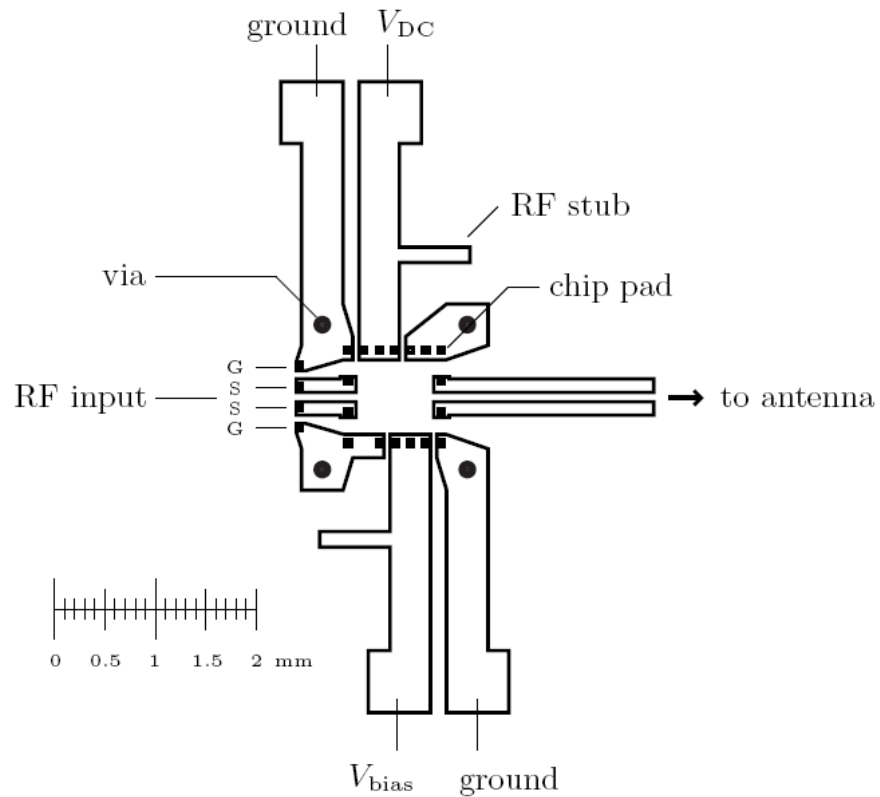
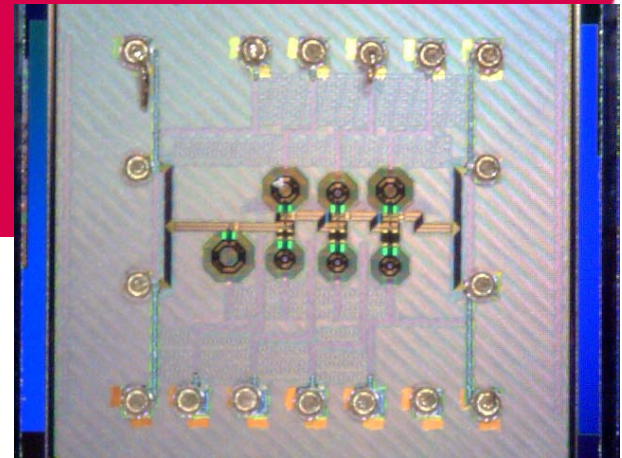
Packaging - Layout

- Single-element antenna
- CMOS power amplifier



Packaging - Chip mount

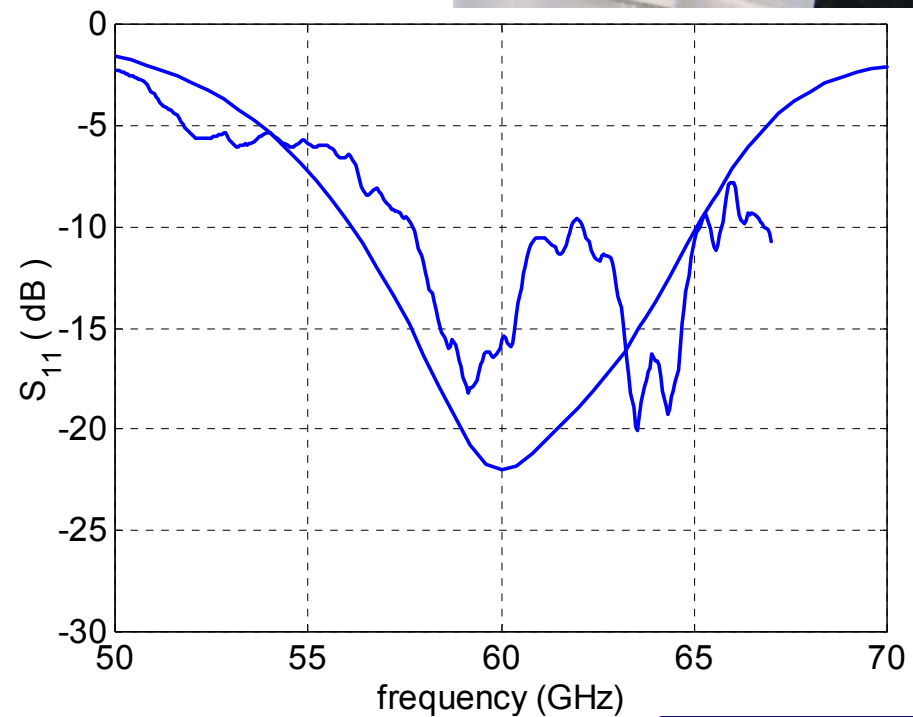
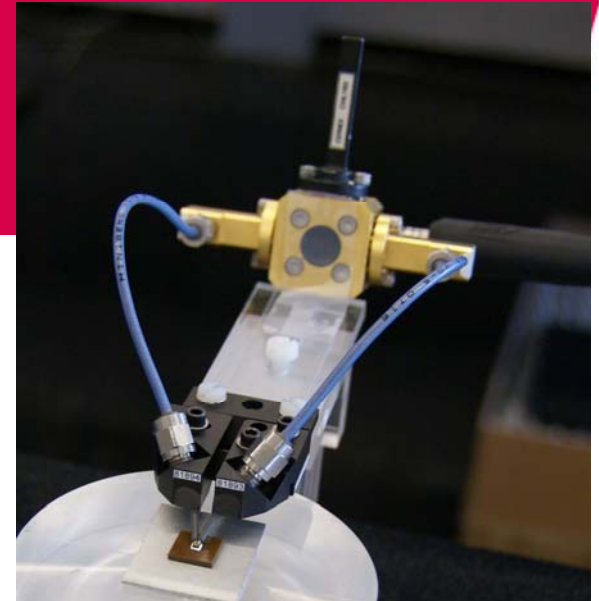
- chip mount PA
- flip-chip interconnection



Packaging

- Antenna performance

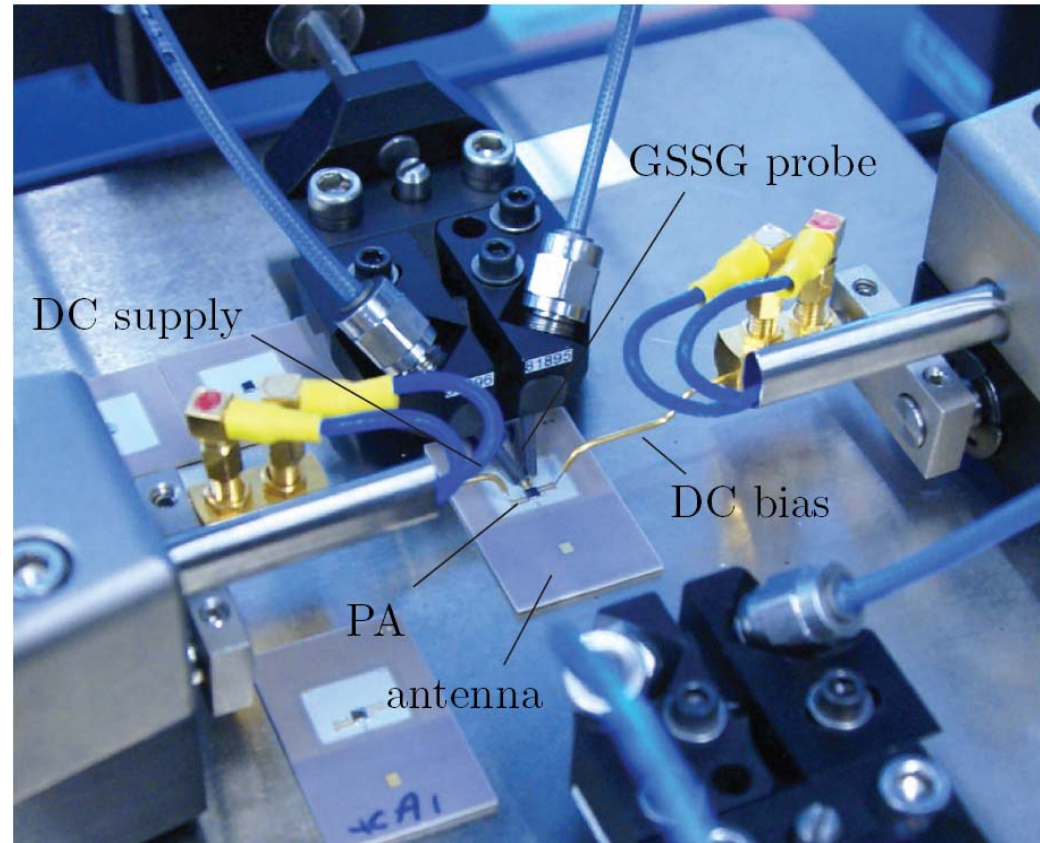
- Antenna measurement
 - balanced measurement
 - bandwidth
 - 57.7 - 65.1 GHz



Packaging

- PA + antenna

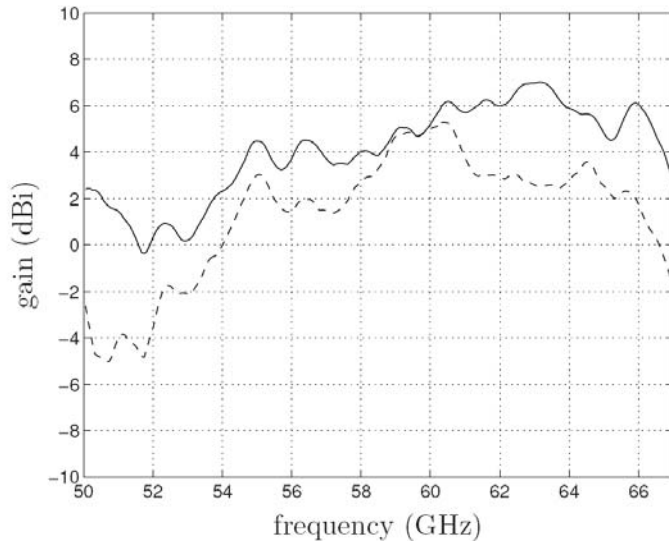
- Probe station
 - MsM group



Packaging

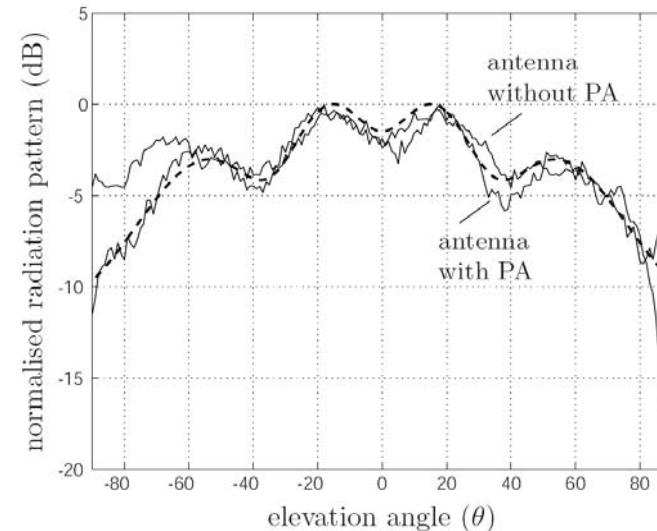
- PA + antenna

gain measurement



- antenna (solid)
- PA + antenna (dashed)

pattern measurement

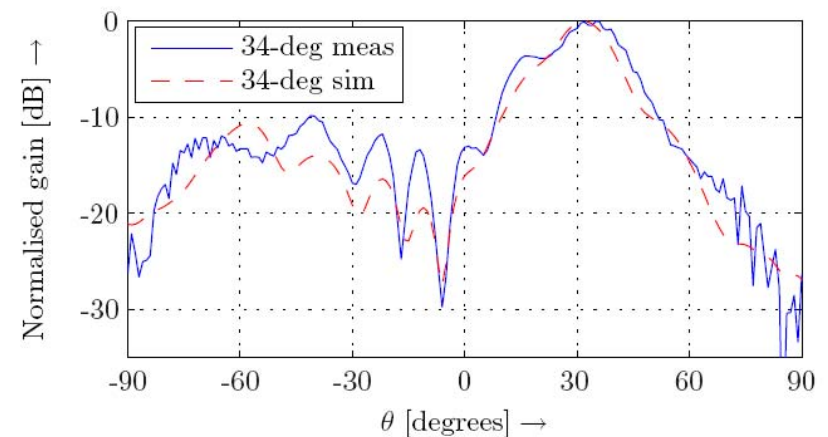
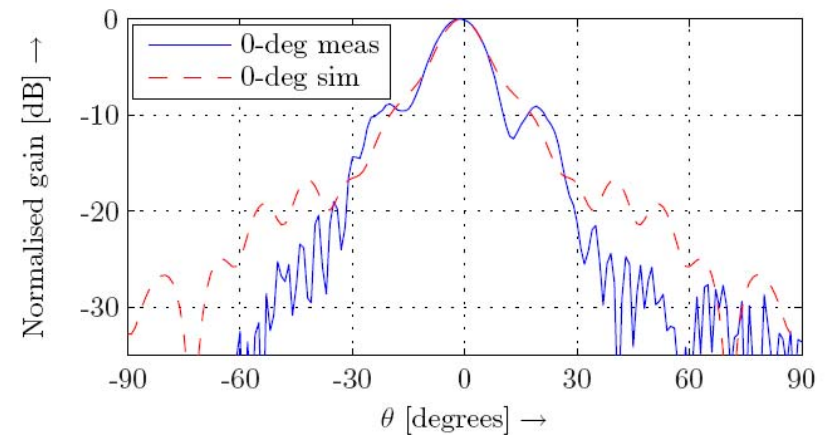
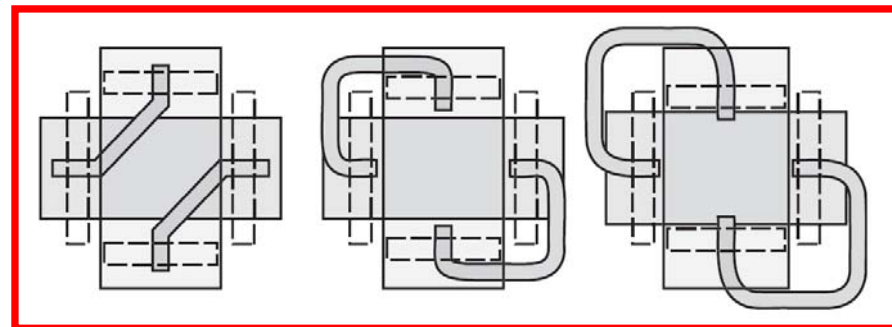
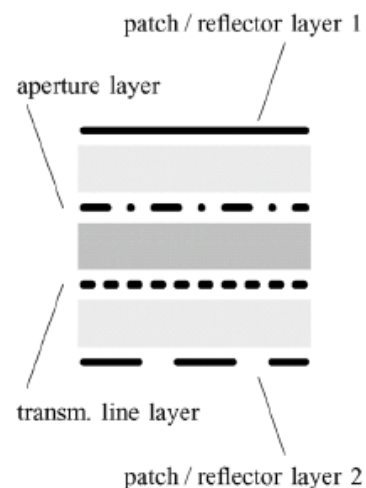
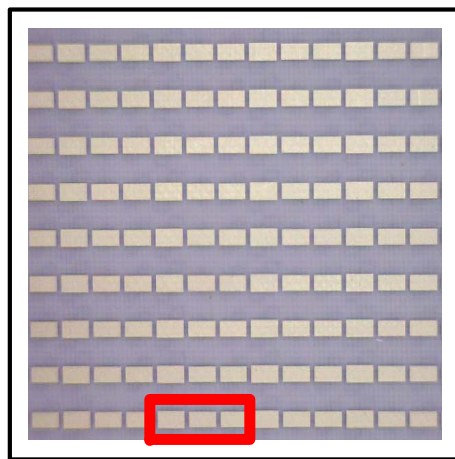


- measurements (solid)
- simulation (dashed)

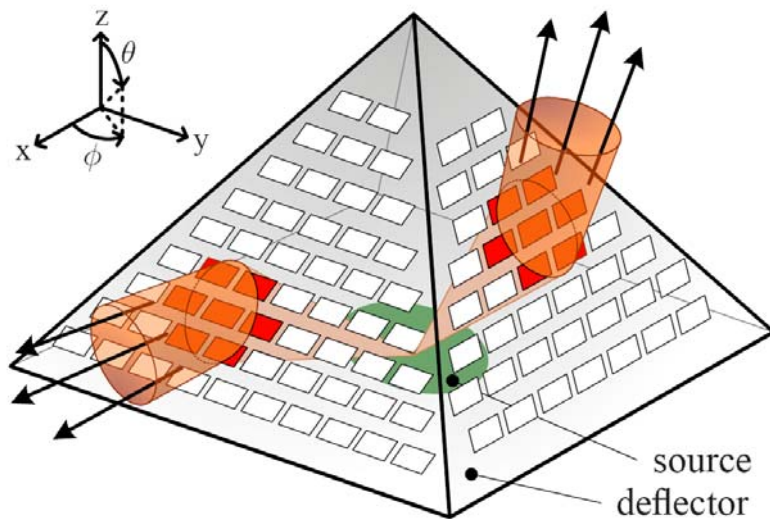
- Flip-chip considerations
 - On-chip inductor
 - Extra plating layer on aluminium pads of the CMOS chip

3D/Conformal antenna array

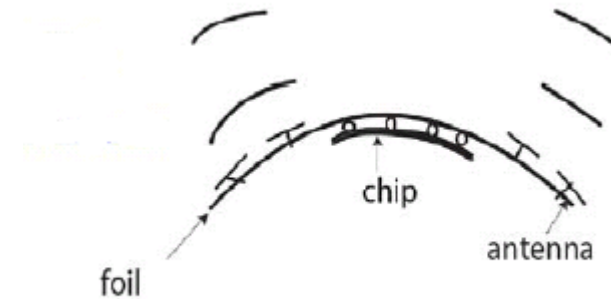
Passive Electromagnetic Deflector



3D/Conformal antenna arrays



Flex PCB technology



Trade-off between directivity, steerability and size of the deflector

Conclusions

- Antenna element
 - high efficiency, large bandwidth
 - MoM model
 - limited number of basis function
 - Optimisation
 - simple, efficient method
- Measurement setup
 - RF probes
 - avoid interconnection problems
 - radiation pattern setup

Conclusions

- Antenna array
 - beam-forming demonstrated
- Packaging
 - integration with PA
 - flip-chip interconnect
 - realization of 7 GHz bandwidth (57.5 to 65.0 GHz) using the packaged PA-antenna
- 3D/Conformal antenna arrays

Almost there...

